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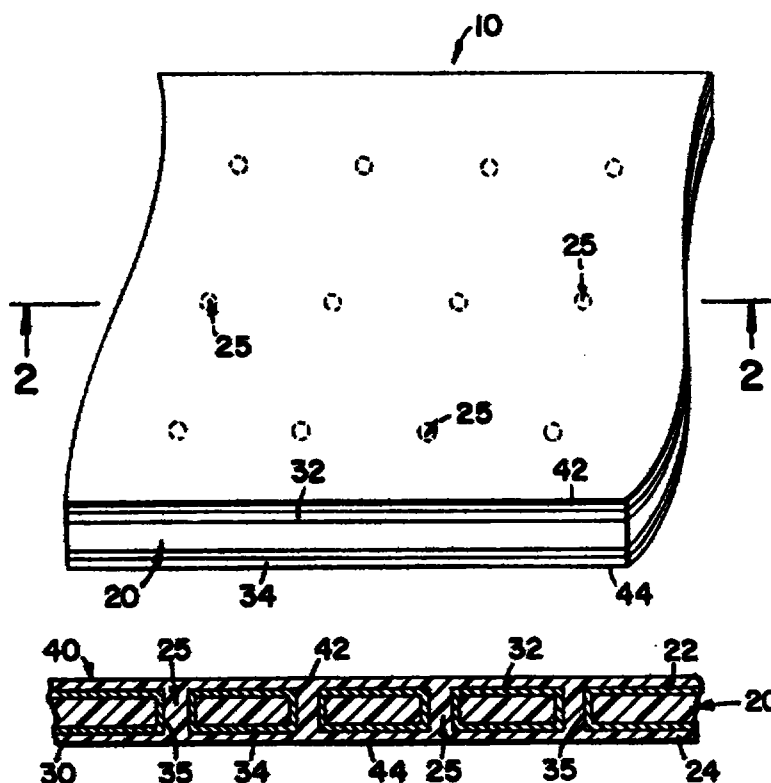
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(54) Title: METALLIZED LAMINATE MATERIAL HAVING ORDERED DISTRIBUTION OF CONDUCTIVE THROUGH HOLES

(57) Abstract

A metallized laminate material (10) for the manufacture of high performance, high density printed wiring boards and the like includes an ordered distribution of via holes (25) electrically interconnecting opposing conductive layers (32, 34) on a dielectric polymeric film substrate (20). Furthermore, opposing photoresist layers (42, 44) substantially cover the conductive layers and vias. The conductive material in the conductive layers (32, 34) and the vias (35) is bonded adhesively to the substrate (20) to provide a high degree of delamination resistance. The production of metallized laminate material (10) is preferably carried out in a roll-to-roll process suitable for high volume, low cost production. In use, an end user may manufacture customized printed wiring boards in small volume runs from the laminate material (10) with a reduced amount of equipment, expertise and cost.



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